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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of

Chi Wah Cheng et al.

Date: April 23, 2003

Serial No.: 10/042,829

Examiner: Kiley Shawn Stoner

Filed: January 8, 2002

Group Art Unit: 1725

For: APPARATUS AND METHOD OF PLACING SOLDER BALLS ONTO A SUBSTRATE

Hon. Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

REQUEST FOR CORRECTED FILING RECEIPT

Please issue a corrected filing receipt for the above application to correct the following errors:

Please correct the fourth inventor's name as follows:

**Chin Pang Chan**

Enclosed is a copy of the Filing Receipt showing the changes in red and a copy of the Declaration showing the correct title and addresses.

It is requested that the U.S. Patent and Trademark Office issue a corrected filing receipt at the earliest possible date.

In the event payment of any fee is inadvertently not enclosed, or if any additional fee during prosecution of this case is not paid, the Patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:  
Commissioner for Patents, Washington, DC 20231,  
on April 23, 2003:

Robert C. Faber

Name of applicant, assignee or  
Registered Representative

Signature

April 23, 2003

Date of Signature

Respectfully submitted,

Robert C. Faber

Registration No.: 24,322

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| APPLICATION NUMBER | FILING DATE | GRP ART UNIT | FIL FEE REC'D | ATTY.DOCKET.NO | DRAWINGS | TOT CLAIMS | IND CLAIMS |
|--------------------|-------------|--------------|---------------|----------------|----------|------------|------------|
| 10/042,829         | 01/08/2002  | 1725         | 942           | P/4076-10      | 9        | 24         | 2          |

## CONFIRMATION NO. 7316

## UPDATED FILING RECEIPT



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000002352  
OSTROLENK FABER GERB & SOFFEN  
1180 AVENUE OF THE AMERICAS  
NEW YORK, NY 100368403

Date Mailed: 05/10/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Chi Wah Cheng, Kwai Chung, CHINA;  
Ping Chun Chong, Kwai Chung, CHINA;  
Chi Fung Chan, Kwai Chung, CHINA;  
Chin Ping Chen, Kwai Chung, CHINA;

*Chin Pang Chan*

## Assignment For Published Patent Application

ASM Automation Assembly Ltd;

## Domestic Priority data as claimed by applicant

## Foreign Applications

If Required, Foreign Filing License Granted 02/13/2002

Projected Publication Date: 07/10/2003

Non-Publication Request: No

Early Publication Request: No

## Title

Apparatus and method of placing solder balls onto a substrate



| UNITED STATES OF AMERICA<br>COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION   |  | OFGS FILE NO.<br>P/4076-10                        |   |                    |                                      |   |  |  |  |                                    |  |  |  |                                    |  |  |  |                                    |                                     |                                      |  |  |  |  |  |  |  |   |  |                        |   |  |   |   |  |  |   |  |                        |   |  |   |   |  |  |
|---|--|---|---|--------------------|--------------------------------------|---|--|--|--|------------------------------------|--|--|--|------------------------------------|--|--|--|------------------------------------|-------------------------------------|--------------------------------------|--|--|--|--|--|--|--|---|--|------------------------|---|--|---|---|--|--|---|--|------------------------|---|--|---|---|--|--|
| <p>As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are named) of the subject matter which is claimed and for which a patent is sought on the invention entitled:</p> <p style="text-align: center;"><b>APPARATUS AND METHOD OF PLACING SOLDER BALLS ONTO A SUBSTRATE</b></p> <hr/> <p>the specification of which is attached hereto, unless the following box is checked:</p> <p><input checked="" type="checkbox"/> was filed on <u>January 8, 2002</u> as United States patent Application Number or PCT International patent application number <u>10/042,829</u> and was amended on _____ (if any).</p> <p>I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.</p> <p>I acknowledge the duty to disclose all information known to be material to patentability in accordance with Title 37, Code of Federal Regulations, §1.56.</p> <p>I hereby claim priority benefits under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate or United States provisional application(s) listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:</p> <p>Prior Foreign or Provisional Application(s)</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: center; width: 25%;">COUNTRY</th> <th style="text-align: center; width: 35%;">APPLICATION NUMBER</th> <th style="text-align: center; width: 25%;">DATE OF FILING<br/>(day, month, year)</th> <th style="text-align: center; width: 15%;">PRIORITY CLAIMED<br/>UNDER 35 U.S.C. 119</th> </tr> </thead> <tbody> <tr><td> </td><td> </td><td> </td><td>YES <u>      </u> NO <u>      </u></td></tr> <tr><td> </td><td> </td><td> </td><td>YES <u>      </u> NO <u>      </u></td></tr> <tr><td> </td><td> </td><td> </td><td>YES <u>      </u> NO <u>      </u></td></tr> </tbody> </table> <p>I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: center; width: 30%;">UNITED STATES<br/>APPLICATION NUMBER</th> <th style="text-align: center; width: 35%;">DATE OF FILING<br/>(day, month, year)</th> <th style="text-align: center; width: 35%;">STATUS<br/>(patented, pending, abandoned)</th> </tr> </thead> <tbody> <tr><td> </td><td> </td><td> </td></tr> <tr><td> </td><td> </td><td> </td></tr> </tbody> </table> <p>I hereby appoint customer no. 2352 OSTROLENK, FABER, GERB &amp; SOFFEN, LLP, and the members of the firm, Samuel H. Weiner - Reg. No. 18,510; Jerome M. Berliner - Reg. No. 18,653; Robert C. Faber - Reg. No. 24,322; Max Moskowitz - Reg. No. 30,576; James A. Finder - Reg. No. 30,173; William O. Gray, III - Reg. No. 30,944; Louis C. Dujmich - Reg. No. 30,625, and Douglas A. Miro - Reg. No. 31,643, as attorneys with full power of substitution and revocation to prosecute this application, to transact all business in the Patent &amp; Trademark Office connected therewith and to receive all correspondence.</p> <p>SEND CORRESPONDENCE TO: <b>OSTROLENK, FABER, GERB &amp; SOFFEN, LLP</b> DIRECT TELEPHONE CALLS TO:<br/> 1180 AVENUE OF THE AMERICAS (212) 382-0700<br/> NEW YORK, NEW YORK 10036-8403<br/> CUSTOMER NO. 2352</p> <p>I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 33%;">FULL NAME OF SOLE OR FIRST INVENTOR<br/><b>Chi Wah CHENG</b></td> <td style="width: 33%;">INVENTOR'S SIGNATURE<br/><i>Chi Wah Cheng</i></td> <td style="width: 34%;">DATE<br/><b>3/20/03</b></td> </tr> <tr> <td colspan="2">RESIDENCE (City and either State or Foreign Country)<br/><b>Kwai Chung, Hong Kong, China</b></td> <td>COUNTRY OF CITIZENSHIP<br/><b>Hong Kong, China</b></td> </tr> <tr> <td colspan="3">POST OFFICE ADDRESS<br/><b>ASM Assembly Automation Ltd, 4/F., Watson Centre, 16 Kung Yip St., Kwai Chung, Hong Kong, China</b></td> </tr> <tr> <td style="width: 33%;">FULL NAME OF SECOND JOINT INVENTOR (IF ANY)<br/><b>Ping Chun CHONG</b></td> <td style="width: 33%;">INVENTOR'S SIGNATURE<br/><i>Ping Chun Chong</i></td> <td style="width: 34%;">DATE<br/><b>3/20/03</b></td> </tr> <tr> <td colspan="2">RESIDENCE (City and either State or Foreign Country)<br/><b>Kwai Chung, Hong Kong, China</b></td> <td>COUNTRY OF CITIZENSHIP<br/><b>Hong Kong, China</b></td> </tr> <tr> <td colspan="3">POST OFFICE ADDRESS<br/><b>ASM Assembly Automation Ltd, 4/F., Watson Centre, 16 Kung Yip St., Kwai Chung, Hong Kong, China</b></td> </tr> </table> |  |   | COUNTRY                                 | APPLICATION NUMBER | DATE OF FILING<br>(day, month, year) | PRIORITY CLAIMED<br>UNDER 35 U.S.C. 119 |  |  |  | YES <u>      </u> NO <u>      </u> |  |  |  | YES <u>      </u> NO <u>      </u> |  |  |  | YES <u>      </u> NO <u>      </u> | UNITED STATES<br>APPLICATION NUMBER | DATE OF FILING<br>(day, month, year) | STATUS<br>(patented, pending, abandoned) |  |  |  |  |  |  | FULL NAME OF SOLE OR FIRST INVENTOR<br><b>Chi Wah CHENG</b> | INVENTOR'S SIGNATURE<br><i>Chi Wah Cheng</i> | DATE<br><b>3/20/03</b> | RESIDENCE (City and either State or Foreign Country)<br><b>Kwai Chung, Hong Kong, China</b> |  | COUNTRY OF CITIZENSHIP<br><b>Hong Kong, China</b> | POST OFFICE ADDRESS<br><b>ASM Assembly Automation Ltd, 4/F., Watson Centre, 16 Kung Yip St., Kwai Chung, Hong Kong, China</b> |  |  | FULL NAME OF SECOND JOINT INVENTOR (IF ANY)<br><b>Ping Chun CHONG</b> | INVENTOR'S SIGNATURE<br><i>Ping Chun Chong</i> | DATE<br><b>3/20/03</b> | RESIDENCE (City and either State or Foreign Country)<br><b>Kwai Chung, Hong Kong, China</b> |  | COUNTRY OF CITIZENSHIP<br><b>Hong Kong, China</b> | POST OFFICE ADDRESS<br><b>ASM Assembly Automation Ltd, 4/F., Watson Centre, 16 Kung Yip St., Kwai Chung, Hong Kong, China</b> |  |  |
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|   |  |   | YES <u>      </u> NO <u>      </u>      |                    |                                      |   |  |  |  |                                    |  |  |  |                                    |  |  |  |                                    |                                     |                                      |  |  |  |  |  |  |  |   |  |                        |   |  |   |   |  |  |   |  |                        |   |  |   |   |  |  |
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|   |  |   | YES <u>      </u> NO <u>      </u>      |                    |                                      |   |  |  |  |                                    |  |  |  |                                    |  |  |  |                                    |                                     |                                      |  |  |  |  |  |  |  |   |  |                        |   |  |   |   |  |  |   |  |                        |   |  |   |   |  |  |
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| FULL NAME OF SECOND JOINT INVENTOR (IF ANY)<br><b>Ping Chun CHONG</b>   | INVENTOR'S SIGNATURE<br><i>Ping Chun Chong</i> | DATE<br><b>3/20/03</b>                            |   |                    |                                      |   |  |  |  |                                    |  |  |  |                                    |  |  |  |                                    |                                     |                                      |  |  |  |  |  |  |  |   |  |                        |   |  |   |   |  |  |   |  |                        |   |  |   |   |  |  |
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